650W, 50V High Power RF LDMOS FETs

Description

The YC0565VPX is a 650-watt capable, high performance, unmatched LDMOS FET, designed for wide-band commercial and industrial applications with frequencies HF to 0.5 GHz. It can be used for both CW and pulse applications.

It is featured for high power and high ruggedness, suitable for Industrial, Scientific and Medical application, as well as FM radio, VHF TV and Aerospace applications.

Typical performance(on 325MHz test board with device soldered):
 V_{DD} = 50 Volts, I_{DQ} = 200 mA, Pulsed CW.(100us,10%), Vgs=3.24V, Vds=50V,ldq=230mA

Freq (MHz)	P3dB (W)	Gain (dB)	Eff (%)
325	325 670		68

- Recommended driver: MR2002VP or MU1503V
- Application board for 2-30/27/40/225/325MHz upon request

YC0565VPX

Features

- · High Efficiency and Linear Gain Operations
- Integrated ESD Protection
- Excellent thermal stability, low HCI drift

- Large Positive and Negative Gate/Source Voltage Range for Improved Class C Operation
- Pb-free, RoHS-compliant

Suitable Applications

- 30-88MHz (Ground communication)
- 54-88MHz (TV VHF I)
- 88-108MHz (FM)
- 160-230MHz (TV VHF III)
- 136-174MHz (Commercial ground communication)
- Laser Exciter
- Synchrotron
- MRI
- Plasma generator
- Weather Radar

Table 1. Maximum Ratings

Tubio I. Muximum Rutingo				
Rating	Symbol	Value	Unit	
DrainSource Voltage	V _{DSS}	+135	Vdc	
GateSource Voltage	V _{GS}	-10 to +10	Vdc	
Operating Voltage	V _{DD}	+55	Vdc	
Storage Temperature Range	Tstg	-65 to +150	°C	
Case Operating Temperature	T _c	+150	°C	
Operating Junction Temperature	TJ	+225	°C	

Table 2. Thermal Characteristics

Characteristic	Symbol	Value	Unit	
Thermal Resistance, Junction to Case	Rejc	0.22	°C/W	
T _C = 85°C, T _J =200°C, DC test		0.22		

Table 3. ESD Protection Characteristics

Test Methodology	Class

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Human Body Model (per JESD22--A114)

Class 2

Table 4. Electrical Characteristics (T_A = 25 $^{\circ}$ C unless otherwise noted)

Characteristic	Symbol	Min	Тур	Max	Unit
DC Characteristics (per half section)					
Drain-Source Voltage	V		135		V
V_{GS} =0, I_{DS} =1.0Ma	V _{(BR)DSS}		133		V
Zero Gate Voltage Drain Leakage Current	I _{DSS}			1	
$(V_{DS} = 75V, V_{GS} = 0 V)$	IDSS	<u>——</u>	<u>——</u>	•	μΑ
Zero Gate Voltage Drain Leakage Current				1	
$(V_{DS} = 50 \text{ V}, V_{GS} = 0 \text{ V})$	I _{DSS}			Į.	μΑ
GateSource Leakage Current	I _{GSS}			1	μА
$(V_{GS} = 10 \text{ V}, V_{DS} = 0 \text{ V})$	I _{GSS}				
Gate Threshold Voltage	$V_{GS}(th)$		2.65		٧
$(V_{DS} = 50V, I_D = 600 \mu A)$	V _{GS} (III)				
Gate Quiescent Voltage	$V_{GS(Q)}$		3.24		V
$(V_{DD} = 50 \text{ V}, I_D = 230 \text{ mA}, \text{Measured in Functional Test})$	▼ GS(Q)		3.24		
Drain source on state resistance			160		mΩ
(Vds=0.1V, Vgs=10V)	Rds(on)		100		11152
Common Source Input Capacitance	Cons	Diss	295	205	pF
$(V_{GS} = 0V, V_{DS} = 50 V, f = 1 MHz)$	Ciss		293		ρι
Common Source Output Capacitance	C _{oss}		75		pF
$(V_{GS} = 0V, V_{DS} = 50 V, f = 1 MHz)$			10		μ-
Common Source Feedback Capacitance	C _{RSS}		1.3		pF
$(V_{GS} = 0V, V_{DS} = 50 V, f = 1 MHz)$			1.3		μ-

 $\textbf{Load Mismatch (In Yingtron Test Fixture, 50 ohm system):} \ V_{DD} = 50 \ Vdc, \ I_{DQ} = 230 \ mA, \ f = 350 MHz, \ pulse \ width: 100 us, \ duty \ cycle: 10\% \ Additional order of the cycle: 10\% \ Additional order or 10\% \ Additional or 10\% \ Additional order or 10\% \ Additional order or 10\% \ Additional order or 10\% \ Additional or 10\% \ Additional order or 10\% \ Additional or 10\% \ Additional order or 10\% \ Additional orde$

Load 10:1 All phase angles, at 650W Pulsed CW Output Power

No Device Degradation

Reference Circuit of Test Fixture Assembly Diagram

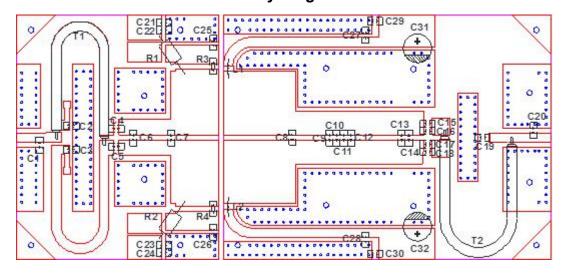


Figure 1. Test Circuit Component Layout (325M)

Table 1. Test Circuit Component Designations and Values (325MHz)

Component	Description	Suggested
		Manufacturer
C1,	20 pF	ATC800B
C2, C3, C4, C5, C15, C16, C17, C18,	470 pF	ATC800B
C22, C23, C27, C28		
C6, C11, C12, C13	10 pF	ATC800B
C7, C8, C9, C10, C14,	18 pF	ATC800B
C19, C20	4.7 pF	ATC800B
C21, C24, C25, C26, C29, C30	Ceramic multilayer capacitor, 10uF, 100V	
R1, R2	270 Ω, 1/4W	
R3, R4	13 Ω	1206
L1, L2	30nH Air core inductance	
C31, C32	Electrolytic Capacitor ,470uF,63V	
PCB	0.508mm [0.020"] thick, εr=3.48, Rogers RO4350B, 1 oz. copper	

TYPICAL CHARACTERISTICS

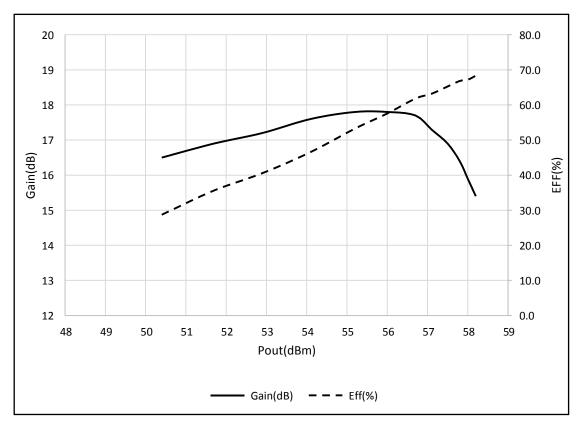
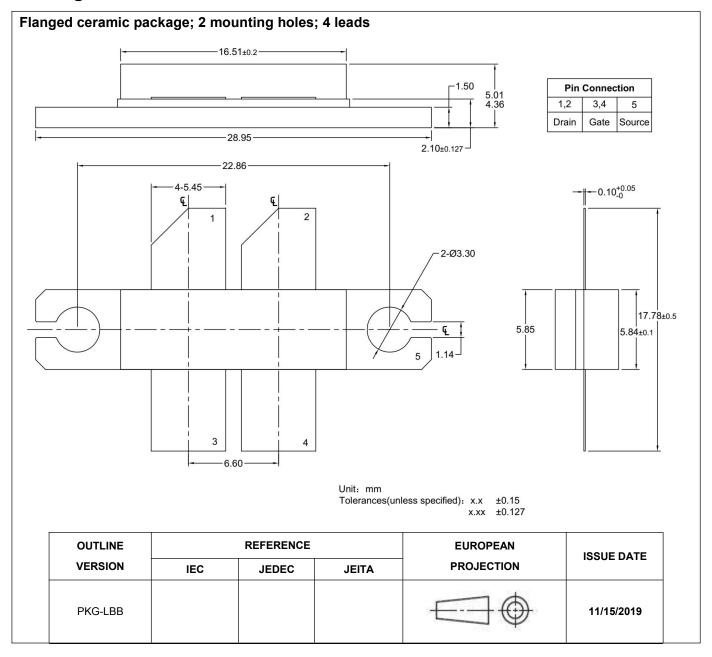


Figure 2: Power Gain and Drain Efficiency as Function of Pout (325MHz)

Package Outline



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Revision history

Table 6. Document revision history

Date	Revision	Datasheet Status
2019/12/17	Rev 1.0	Preliminary Datasheet Creation

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